

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application. Please add new claim 21:

LISTING OF CLAIMS:

1. (Previously Presented) An electronic apparatus comprising:

an electronic circuit board;

an electrically conductive casing for encasing said electronic circuit board;

a semiconductor element module electrically connected to said electronic circuit board via a plurality of lead terminals, said semiconductor element module having a column-shaped section, an axis of said column-shaped section being parallel to a direction of extension of said lead terminals; and

a resin fixture intervening between said electrically conductive casing and said semiconductor element module, said resin fixture mounted with said semiconductor element module and fitted to said electrically conductive casing, said resin fixture having a cylinder-shaped section for retaining, in its inner periphery, said column-shaped section of said semiconductor element module, an outer periphery surface of said cylinder-shaped section being plated and an inner periphery surface of said cylinder-shaped section not being plated.
2. (Canceled)

3. (Canceled)

4. (Original) An electronic apparatus according to claim 1, wherein

said semiconductor element module has a raised portion formed on its outer surface at a site where said semiconductor element module is fitted to said resin fixture, and wherein

said resin fixture has a recessed portion formed in its inner surface at a site where said semiconductor module is mounted, said recessed portion being fitted to said raised portion.

5. (Original) An electronic apparatus according to claim 1, wherein

said semiconductor element module has an externally threaded portion formed on its outer surface at a site where said semiconductor element module is fitted to said resin fixture, and wherein

said resin fixture has an internally threaded portion formed in its inner surface at a site where said semiconductor module is mounted, said externally threaded portion being screwed into said internally threaded portion.

6. (Original) An electronic apparatus according to claim 1, wherein

said semiconductor element module has a recessed portion formed in its outer surface at a site where said semiconductor element module is fitted to said resin fixture, and wherein

said resin fixture has a raised portion formed on its inner surface at a site where said semiconductor module is mounted, said raised portion being fitted to said recessed portion.

7. (Canceled)

8. (Original) An electronic apparatus according to claim 1, wherein said electronic circuit board is bonded to and encased in said electrically conductive casing by use of an electrically conductive adhesive sheet.

9. (Canceled)

10. (Original) An electronic apparatus according to claim 1, wherein said semiconductor element module has a raised portion formed on its outer surface at a site where said semiconductor element module is fitted to said resin fixture and wherein

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said resin fixture has a notched portion formed in its outer wall and has a recessed portion formed in the inner surface at a site where said semiconductor module is mounted, said recessed portion being fitted to said raised portion, and wherein

said electrically conductive casing has a hooked portion which fits said notched portion of said resin fixture.

11. (Original) An electronic apparatus according to claim 1, wherein

said semiconductor element module has an externally threaded portion formed on its outer surface at a site where said semiconductor element module is fitted to said resin fixture, and wherein

said resin fixture has a notched portion formed in its outer wall and has an internally threaded portion formed in its inner surface at a site where said semiconductor module is mounted, said externally threaded portion being screwed into said internally threaded portion, and wherein

said electrically conductive casing has a hooked portion which fits said notched portion of said resin fixture.

12. (Original) An electronic apparatus according to claim 1, wherein

said semiconductor element module has a recessed portion formed in its outer surface at a site where said semiconductor element module is fitted to said resin fixture, and wherein

said resin fixture has a notched portion formed in its outer wall and has a raised portion formed on its inner surface at a site where said semiconductor module is mounted, said raised portion being fitted to said recessed portion, and wherein

said electrically conductive casing has a hooked portion which fits said notched portion of said resin fixture.

13. (Original) An electronic apparatus according to claim 1, wherein

said semiconductor element module has a raised portion formed on its outer surface at a site where said semiconductor element module is fitted to said resin fixture, and wherein

said resin fixture has a protrusion formed on its outer surface and has a recessed portion formed in its inner surface at a site where said semiconductor module is mounted, said recessed portion being fitted to said raised portion, and wherein

said electrically conductive casing has an insertion hole which receives said protrusion of said resin fixture.

14. (Original) An electronic apparatus according to claim 1, wherein

said semiconductor element module has an externally threaded portion formed on its outer surface at a site where said semiconductor element module is fitted to said resin fixture, and wherein

said resin fixture has a protrusion formed on its outer surface and has an internally threaded portion formed in its inner surface at a site where said semiconductor module is mounted, said externally threaded portion being screwed into said internally threaded portion, and wherein

said electrically conductive casing has an insertion hole which receives said protrusion of said resin fixture.

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15. (Original) An electronic apparatus according to claim 1, wherein

said semiconductor element module has a recessed portion formed in its outer surface at a site where said semiconductor element module is fitted to said resin fixture, and wherein

said resin fixture has a protrusion formed on its outer surface and has a raised portion formed on its inner surface at a site where said semiconductor module is mounted, said raised portion being fitted to said recessed portion, and wherein

said electrically conductive casing has an insertion hole which receives said protrusion of said resin fixture.

16. (Canceled)

17. (Canceled)

18. (Canceled)

19. (Canceled)

20. (Canceled)

21. (New) An electronic apparatus comprising:

an electronic circuit board;

an electrically conductive casing for encasing said electronic circuit board;

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a coaxial optical semiconductor element module electrically connected to said electronic circuit board via a plurality of lead terminals, said semiconductor element module having a column-shaped section, an axis of said column-shaped being parallel to a direction of extension of said lead terminals; and

a resin fixture intervening between said electrically conductive casing and said semiconductor element module, said resin fixture mounted with said semiconductor element module and fitted to said electrically conductive casing, said resin fixture having an opening having an inner diameter which is larger than an outer diameter of said column-shaped section of said semiconductor element module, said opening retaining said column-shaped section therein, an outer periphery surface of said resin fixture being metal plated and an inside surface of said opening not being metal plated.
